



100% Material Declaration Data Sheet QFG32

PK238 (v1.0) December 12, 2007

Material Declaration Data Sheet

Average Weight: 0.064 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.00216	3.38 %
	Silicon	7440-21-3	100.00		0.00216	
Die Attach Material					0.00062	0.98%
	Resin	Trade Secret	21.00		0.000131	
	Silver	7440-22-4	70.00		0.000437	
	Metal Oxide	N/A	3.00		0.000019	
	Amine	68038-01-7	3.00		0.000019	
	Gamma Butyrolactone	96-48-0	3.00		0.000019	
Mold Compound					0.02695	42.13%
	Resin	Trade Secret	16.00		0.00431	
	Silica	60676-86-0	84.00		0.02264	
Leadframe					0.03254	50.86%
	Copper	7440-50-8	97.50		0.031726	
	Iron	7439-89-5	2.35		0.000765	
	Phosporus	7723-14-0	0.03		0.000010	
	Zinc	7440-66-6	0.12		0.000039	
Leadframe Plating					0.000608	0.95%
	Silver	7440-22-4	100.00		0.000608	
Bond Wire					0.00084	1.32%
	Gold	7440-57-5	100.00		0.00084	
External Plating					0.00025	0.38%
	Tin	7440-31-5	100.00		0.00025	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
12/12/07	1.0	Initial release.